Amendments to the Specification:

Please replace the paragraph which begins on line 17 of page 13 and ends on line 19 of page 14 with the following amended paragraph:

FIG. 6 illustrates the inside of the seal curing device when the seal is cured by a batch process, i.e. when a plurality of panel bodies 110 are simultaneously processed during a single seal curing process. While the upper and lower heating plates 200 and the pressing mechanism 210 are identical to those described in connection with FIG. 2, the workpiece 100 to be processed includes a plurality of stacked panel bodies 110. Similarly to the workpiece illustrated in FIG. 2, the workpiece 100 includes the upper and lower dummy glasses 20 at the uppermost and lowermost stages thereof. The buffer plate 300 similar to the one illustrated in FIG. 2 is disposed on the lower dummy glass 20, and the panel body 110 is disposed on the plate 300 aligned therewith. On this panel body, the plurality of panel bodies 110 are mounted, and the buffer plate 300 is disposed at each gap between the adjoining panel bodies 110 and aligned so that the opening overlaps each display area of each panel body 110 and that the lattice member overlaps the seal region. On the uppermost panel body 110, the upper buffer plate 300 and the upper dummy glass 20 are mounted, similarly to the configuration illustrated in FIG. 2. This workpiece 100 is also heated (at a temperature of, for example, 150.degree. C.) by sandwiching it between the upper and lower heating plates 200 and applying pressure therethrough, so that the seal region of the panel body 110 at each stage can be heated while being pressed by the buffer plate 300, thereby curing the seal material 12. Pressing of the display area for each panel of each panel body 110 is also avoided in such a seal curing process of the batch type because the opening 302 (see FIG. 3) of the buffer plate 300 is superposed on the display area. This is illustrated in Fig. 6 by downwardly directed arrows showing the manner in which

downward force from the pressing mechanism 210 is applied to the upper surface of the uppermost panel body 110 in areas where the adjacent buffer plate 300 exists but not in areas where there are openings 302 in the adjacent buffer plate 300. Similarly, upwardly directed arrows in Fig. 6 show the manner in which upward force from the pressing mechanism 210 is applied to the lower surface of the lowermost panel body 110 in areas where the adjacent buffer plate 300 exists but not in areas where there are openings 302 in the adjacent buffer plate 300. In this way, the gap in the cell can be uniformly maintained at the panel surface without providing any spacers in the cell space when the seal is cured.